

SCLS257L – DECEMBER 1995 – REVISED JULY 2003

- description/ordering information**

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pull-down resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

Pin	Signal
1	1OE
2	1A
3	1Y
4	2OE
5	2A
6	2Y
7	GND
8	3Y
9	3A
10	3OE
11	4Y
12	4A
13	4OE
14	VCC

NC – No internal connection

T _A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	SN74AHC126N	SN74AHC126N
	SOIC – D	Tube	SN74AHC126D	AHC126
		Tape and reel	SN74AHC126DR	
	SOP – NS	Tape and reel	SN74AHC126NSR	AHC126
	SSOP – DB	Tape and reel	SN74AHC126DBR	HA126
	TSSOP – PW	Tube	SN74AHC126PW	HA126
		Tape and reel	SN74AHC126PWR	
TVSOP – DGV	Tape and reel	SN74AHC126DGVR	HA126	
–55°C to 125°C	CDIP – J	Tube	SNJ54AHC126J	SNJ54AHC126J
	CFP – W	Tube	SNJ54AHC126W	SNJ54AHC126W
	LCCC – FK	Tube	SNJ54AHC126FK	SNJ54AHC126FK

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

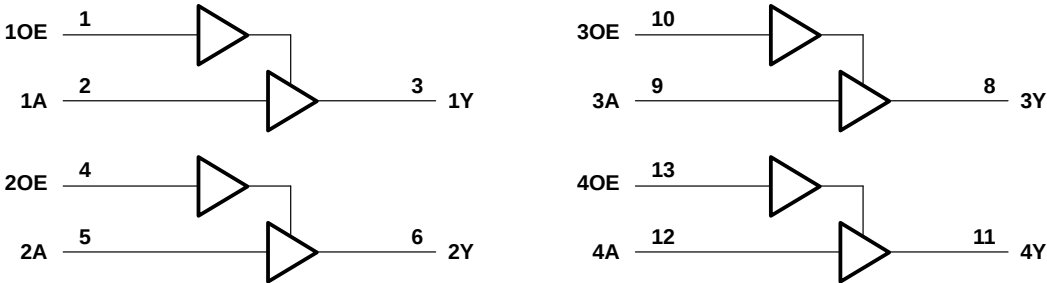
SN54AHC126, SN74AHC126
QUADRUPLE BUS BUFFER GATES
WITH 3-STATE OUTPUTS

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FUNCTION TABLE
(each buffer)

INPUTS		OUTPUT Y
OE	A	
H	H	H
H	L	L
L	X	Z

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, N, NS, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Output voltage range, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V_{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
D package	86°C/W
DB package	96°C/W
DGV package	127°C/W
N package	80°C/W
NS package	76°C/W
PW package	113°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

SN54AHC126, SN74AHC126 QUADRUPLE BUS BUFFER GATES WITH 3-STATE OUTPUTS

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recommended operating conditions (see Note 3)

			SN54AHC126		SN74AHC126		UNIT
			MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage		2	5.5	2	5.5	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5		1.5		V
		V _{CC} = 3 V	2.1		2.1		
		V _{CC} = 5.5 V	3.85		3.85		
V _{IL}	Low-level input voltage	V _{CC} = 2 V		0.5		0.5	V
		V _{CC} = 3 V		0.9		0.9	
		V _{CC} = 5.5 V		1.65		1.65	
V _I	Input voltage		0	5.5	0	5.5	V
V _O	Output voltage		0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 2 V		–50		–50	μA
		V _{CC} = 3.3 V ± 0.3 V		–4		–4	mA
		V _{CC} = 5 V ± 0.5 V		–8		–8	
I _{OL}	Low-level output current	V _{CC} = 2 V		50		50	μA
		V _{CC} = 3.3 V ± 0.3 V		4		4	mA
		V _{CC} = 5 V ± 0.5 V		8		8	
Δt/Δv	Input transition rise or fall rate	V _{CC} = 3.3 V ± 0.3 V		100		100	ns/V
		V _{CC} = 5 V ± 0.5 V		20		20	
T _A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AHC126		SN74AHC126		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = –50 μA	2 V	1.9	2		1.9		1.9		V
		3 V	2.9	3		2.9		2.9		
		4.5 V	4.4	4.5		4.4		4.4		
	I _{OH} = –4 mA	3 V	2.58			2.48		2.48		
	I _{OH} = –8 mA	4.5 V	3.94			3.8		3.8		
V _{OL}	I _{OL} = 50 μA	2 V			0.1		0.1		0.1	V
		3 V			0.1		0.1		0.1	
		4.5 V			0.1		0.1		0.1	
	I _{OL} = 4 mA	3 V			0.36		0.5		0.44	
	I _{OL} = 8 mA	4.5 V			0.36		0.5		0.44	
I _I	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1*		±1	μA
I _{OZ}	V _O = V _{CC} or GND	5.5 V			±0.25		±2.5		±2.5	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			4		40		40	μA
C _i	V _I = V _{CC} or GND	5 V		4	10				10	pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.



SN54AHC126, SN74AHC126

QUADRUPLE BUS BUFFER GATES

WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54AHC126		SN74AHC126		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	C _L = 15 pF	5.6*	8*	1*	9.5*	1	9.5	ns	
t _{PHL}				5.6*	8*	1*	9.5*	1	9.5		
t _{PZH}	OE	Y	C _L = 15 pF	5.4*	8*	1*	9.5*	1	9.5	ns	
t _{PZL}				5.4*	8*	1*	9.5*	1	9.5		
t _{PHZ}	OE	Y	C _L = 15 pF	7*	9.7*	1*	11.5*	1	11.5	ns	
t _{PLZ}				7*	9.7*	1*	11.5*	1	11.5		
t _{PLH}	A	Y	C _L = 50 pF	8.1	11.5	1	13	1	13	ns	
t _{PHL}				8.1	11.5	1	13	1	13		
t _{PZH}	OE	Y	C _L = 50 pF	7.9	11.5	1	13	1	13	ns	
t _{PZL}				7.9	11.5	1	13	1	13		
t _{PHZ}	OE	Y	C _L = 50 pF	9.5	13.2	1	15	1	15	ns	
t _{PLZ}				9.5	13.2	1	15	1	15		
t _{sk(o)}			C _L = 50 pF	1.5**				1.5		ns	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

** On products compliant to MIL-PRF-38535, this parameter does not apply.

switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54AHC126		SN74AHC126		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	C _L = 15 pF	3.8*	5.5*	1*	6.5*	1	6.5	ns	
t _{PHL}				3.8*	5.5*	1*	6.5*	1	6.5		
t _{PZH}	OE	Y	C _L = 15 pF	3.6*	5.1*	1*	6*	1	6	ns	
t _{PZL}				3.6*	5.1*	1*	6*	1	6		
t _{PHZ}	OE	Y	C _L = 15 pF	4.6*	6.8*	1*	8*	1	8	ns	
t _{PLZ}				4.6*	6.8*	1*	8*	1	8		
t _{PLH}	A	Y	C _L = 50 pF	5.3	7.5	1	8.5	1	8.5	ns	
t _{PHL}				5.3	7.5	1	8.5	1	8.5		
t _{PZH}	OE	Y	C _L = 50 pF	5.1	7.1	1	8	1	8	ns	
t _{PZL}				5.1	7.1	1	8	1	8		
t _{PHZ}	OE	Y	C _L = 50 pF	6.1	8.8	1	10	1	10	ns	
t _{PLZ}				6.1	8.8	1	10	1	10		
t _{sk(o)}			C _L = 50 pF	1**				1		ns	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

** On products compliant to MIL-PRF-38535, this parameter does not apply.

SN54AHC126, SN74AHC126
QUADRUPLER BUS BUFFER GATES
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noise characteristics, $V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$ (see Note 4)

PARAMETER	SN74AHC126		UNIT
	MIN	MAX	
$V_{OL(P)}$ Quiet output, maximum dynamic V_{OL}		0.8	V
$V_{OL(V)}$ Quiet output, minimum dynamic V_{OL}		–0.8	V
$V_{OH(V)}$ Quiet output, minimum dynamic V_{OH}	4.4		V
$V_{IH(D)}$ High-level dynamic input voltage	3.5		V
$V_{IL(D)}$ Low-level dynamic input voltage		1.5	V

NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

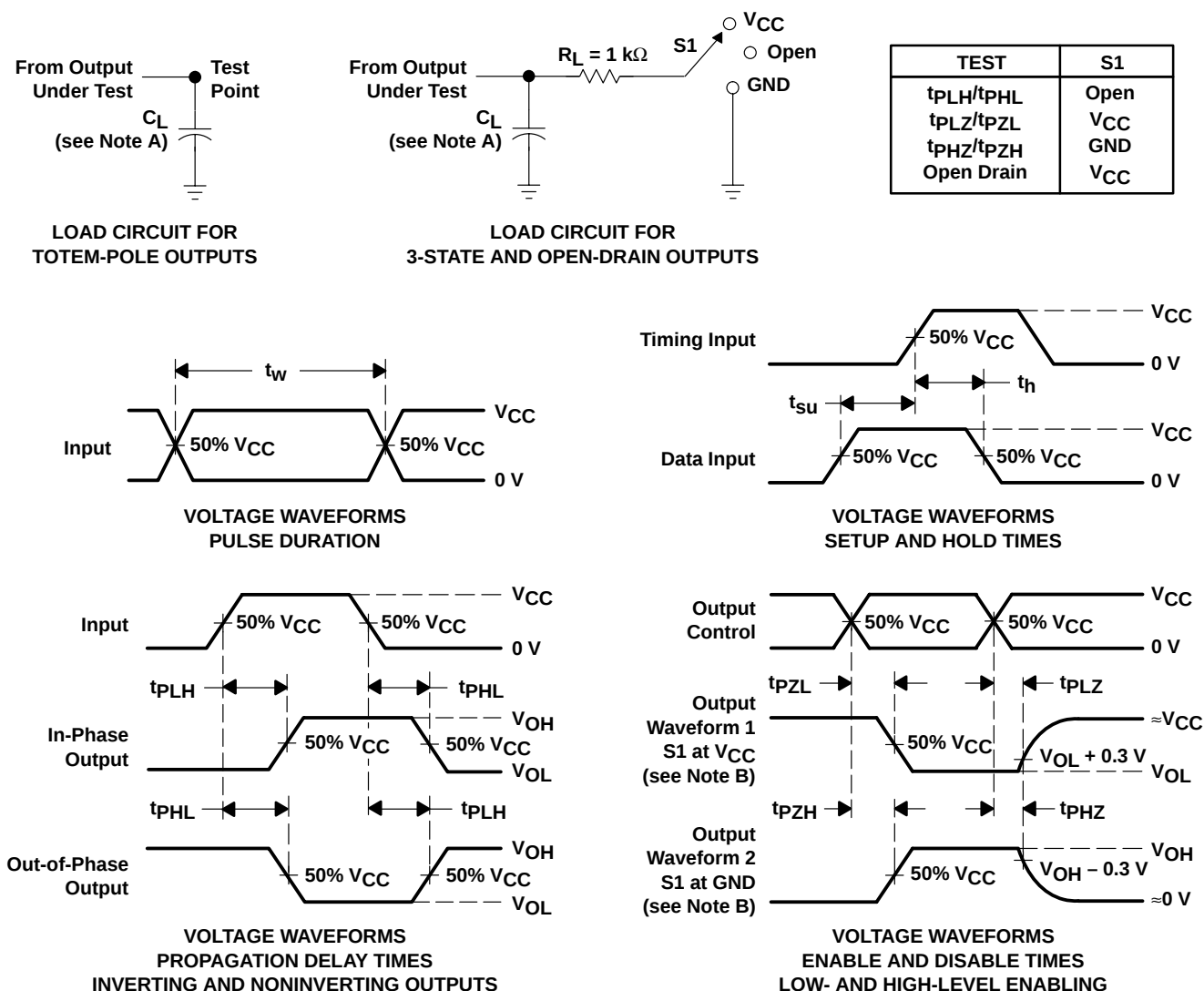
PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load, $f = 1\text{ MHz}$	14	pF



SN54AHC126, SN74AHC126 QUADRUPLE BUS BUFFER GATES WITH 3-STATE OUTPUTS

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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 D. The outputs are measured one at a time with one input transition per measurement.
 E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9686201Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9686201Q2A SNJ54AHC 126FK	Samples
5962-9686201QCA	ACTIVE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		Samples
5962-9686201QDA	ACTIVE	CFP	W	14		TBD	Call TI	Call TI	-55 to 125		Samples
SN74AHC126D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC126	Samples
SN74AHC126DBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI	-40 to 85		
SN74AHC126DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA126	Samples
SN74AHC126DBRE4	ACTIVE	SSOP	DB	14		TBD	Call TI	Call TI	-40 to 85		Samples
SN74AHC126DBRG4	ACTIVE	SSOP	DB	14		TBD	Call TI	Call TI	-40 to 85		Samples
SN74AHC126DE4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI	-40 to 85		Samples
SN74AHC126DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC126	Samples
SN74AHC126DGVR	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA126	Samples
SN74AHC126DGVRE4	ACTIVE	TVSOP	DGV	14		TBD	Call TI	Call TI	-40 to 85		Samples
SN74AHC126DGVRG4	ACTIVE	TVSOP	DGV	14		TBD	Call TI	Call TI	-40 to 85		Samples
SN74AHC126DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC126	Samples
SN74AHC126DRE4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI	-40 to 85		Samples
SN74AHC126DRG4	ACTIVE	SOIC	D	14		TBD	Call TI	Call TI	-40 to 85		Samples
SN74AHC126N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74AHC126N	Samples
SN74AHC126NE4	ACTIVE	PDIP	N	14		TBD	Call TI	Call TI	-40 to 85		Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AHC126NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHC126	Samples
SN74AHC126NSRE4	ACTIVE	SO	NS	14		TBD	Call TI	Call TI	-40 to 85		Samples
SN74AHC126NSRG4	ACTIVE	SO	NS	14		TBD	Call TI	Call TI	-40 to 85		Samples
SN74AHC126PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA126	Samples
SN74AHC126PWE4	ACTIVE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 85		Samples
SN74AHC126PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA126	Samples
SN74AHC126PWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 85		
SN74AHC126PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA126	Samples
SN74AHC126PWRE4	ACTIVE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 85		Samples
SN74AHC126PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HA126	Samples
SNJ54AHC126FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9686201Q2A SNJ54AHC 126FK	Samples
SNJ54AHC126J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9686201QC A SNJ54AHC126J	Samples
SNJ54AHC126W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9686201QD A SNJ54AHC126W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54AHC126, SN74AHC126 :

● Catalog: [SN74AHC126](#)

● Military: [SN54AHC126](#)

NOTE: Qualified Version Definitions:

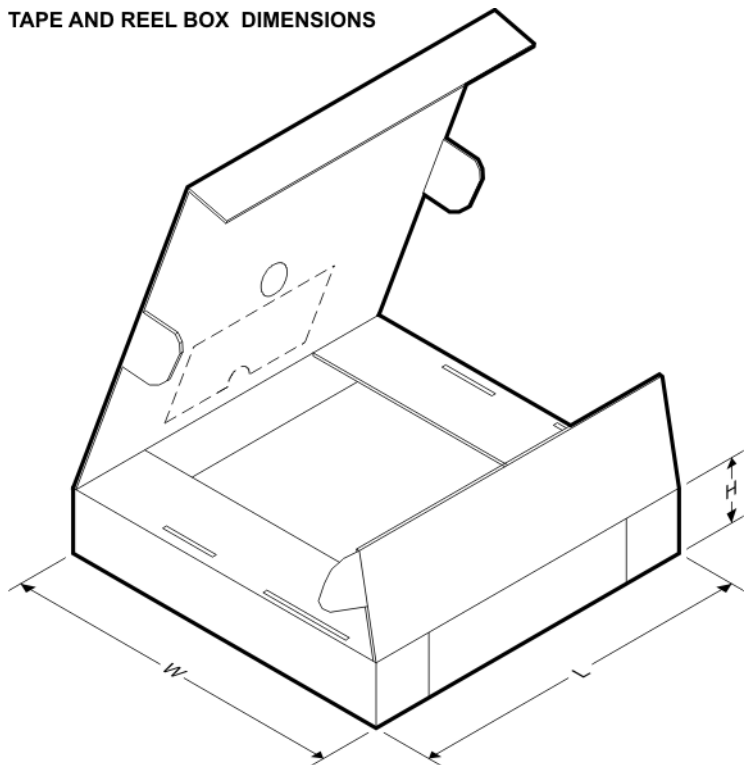
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC126DBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74AHC126DGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74AHC126DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHC126NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AHC126PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC126DBR	SSOP	DB	14	2000	367.0	367.0	38.0
SN74AHC126DGVR	TVSOP	DGV	14	2000	367.0	367.0	35.0
SN74AHC126DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74AHC126NSR	SO	NS	14	2000	367.0	367.0	38.0
SN74AHC126PWR	TSSOP	PW	14	2000	367.0	367.0	35.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

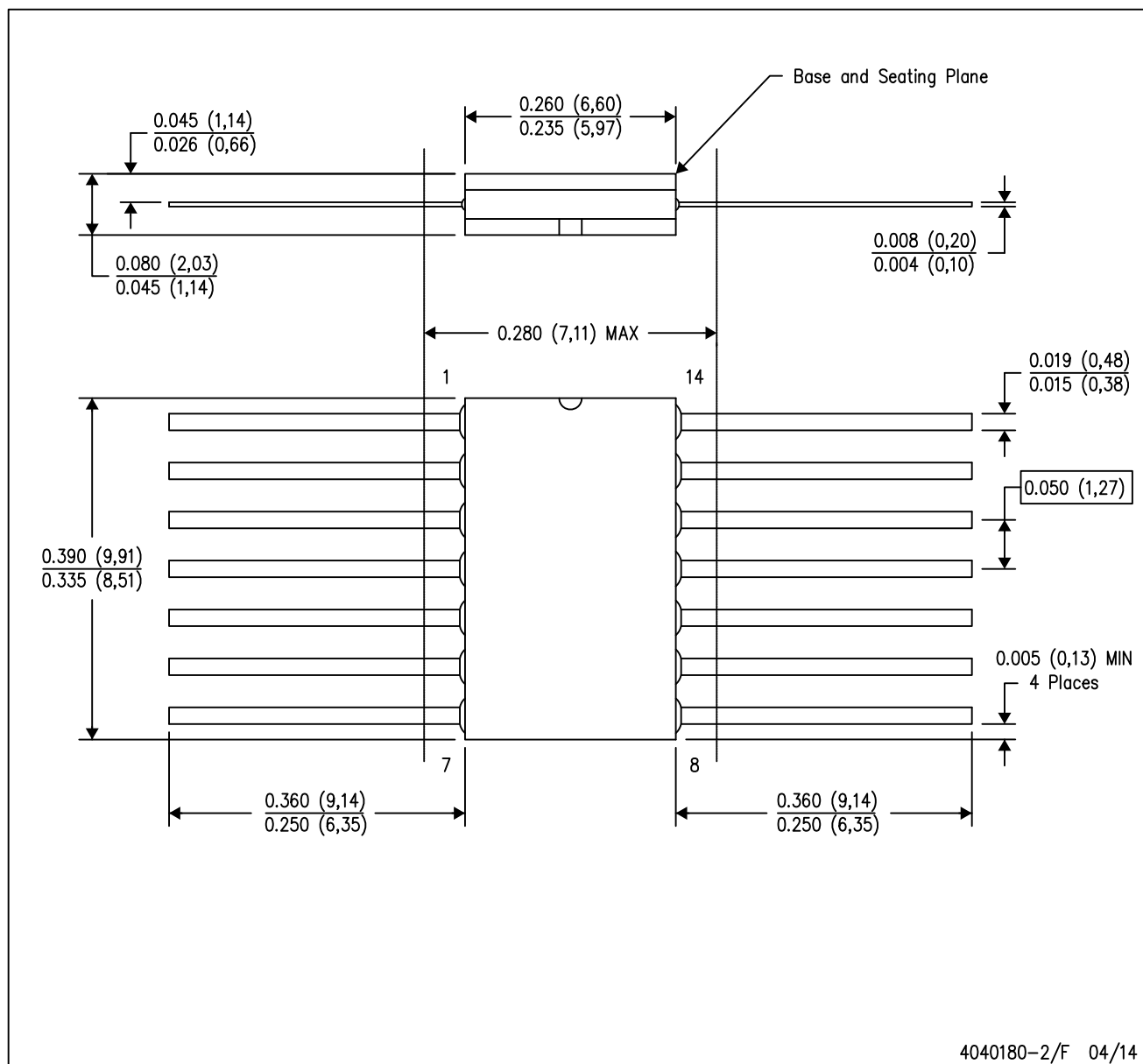


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- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

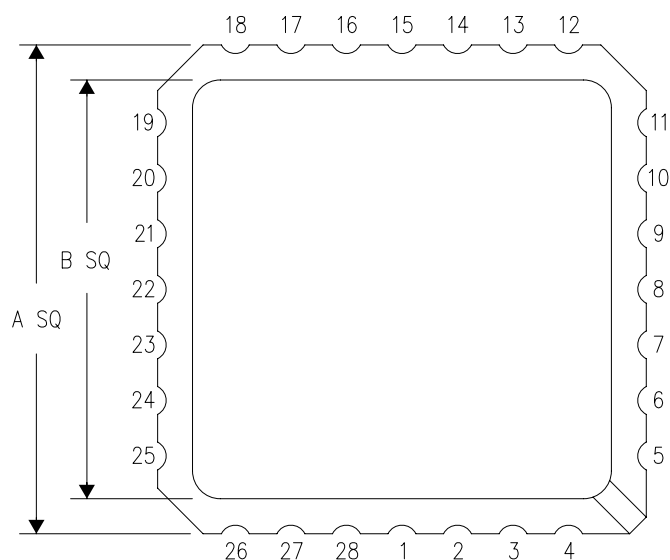
CERAMIC DUAL FLATPACK



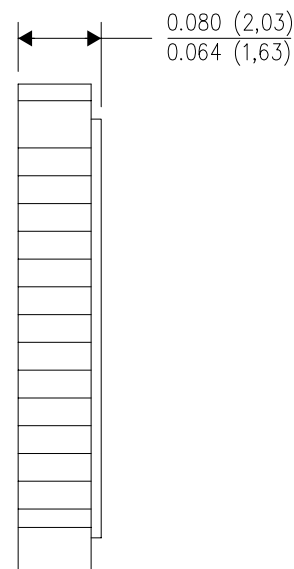
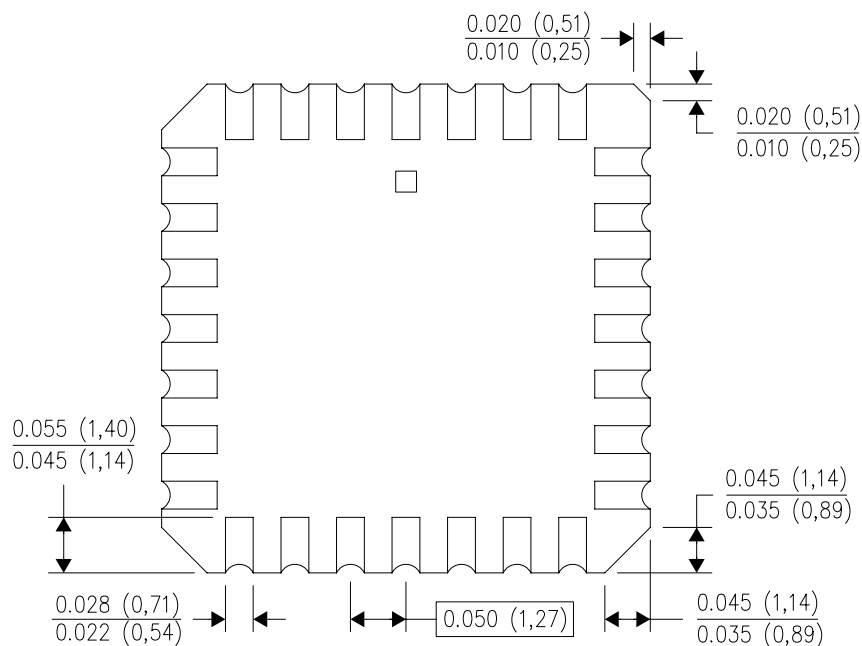
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



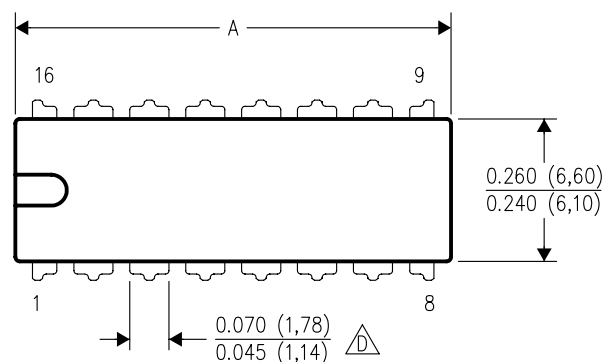
4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

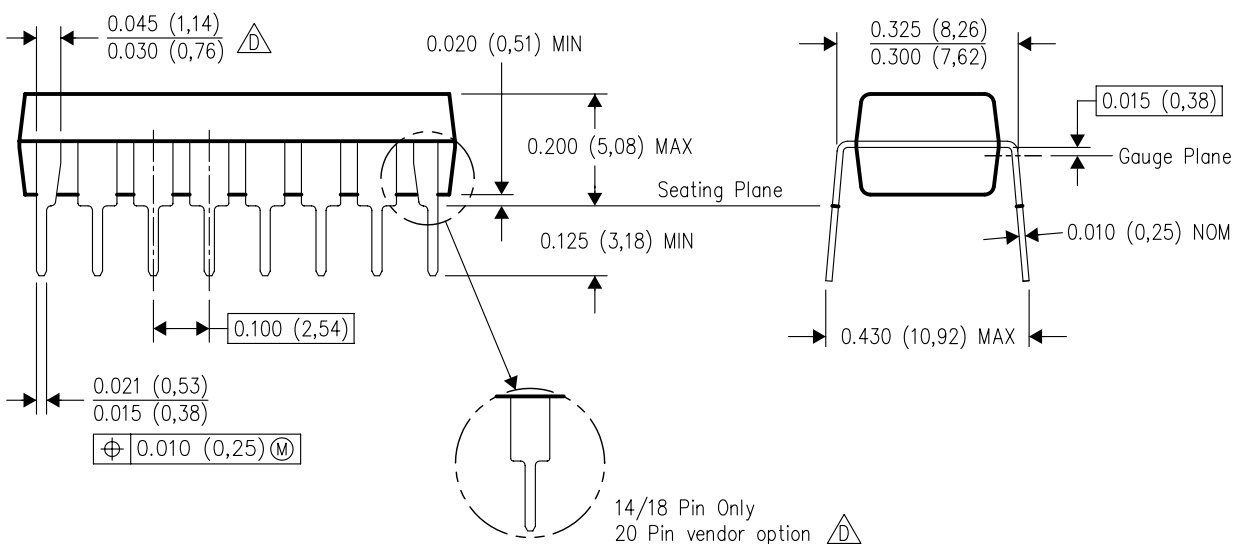
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

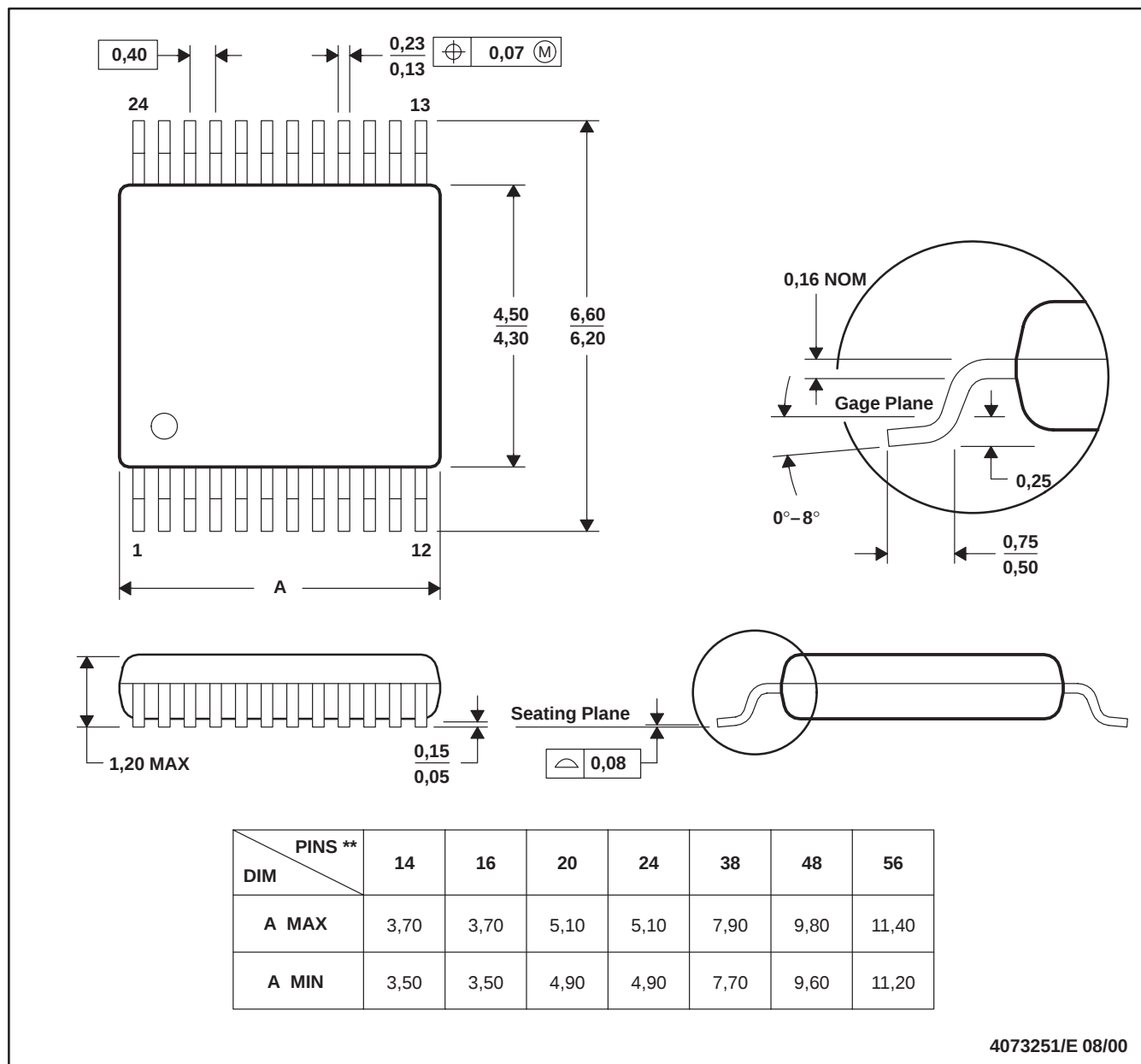
NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

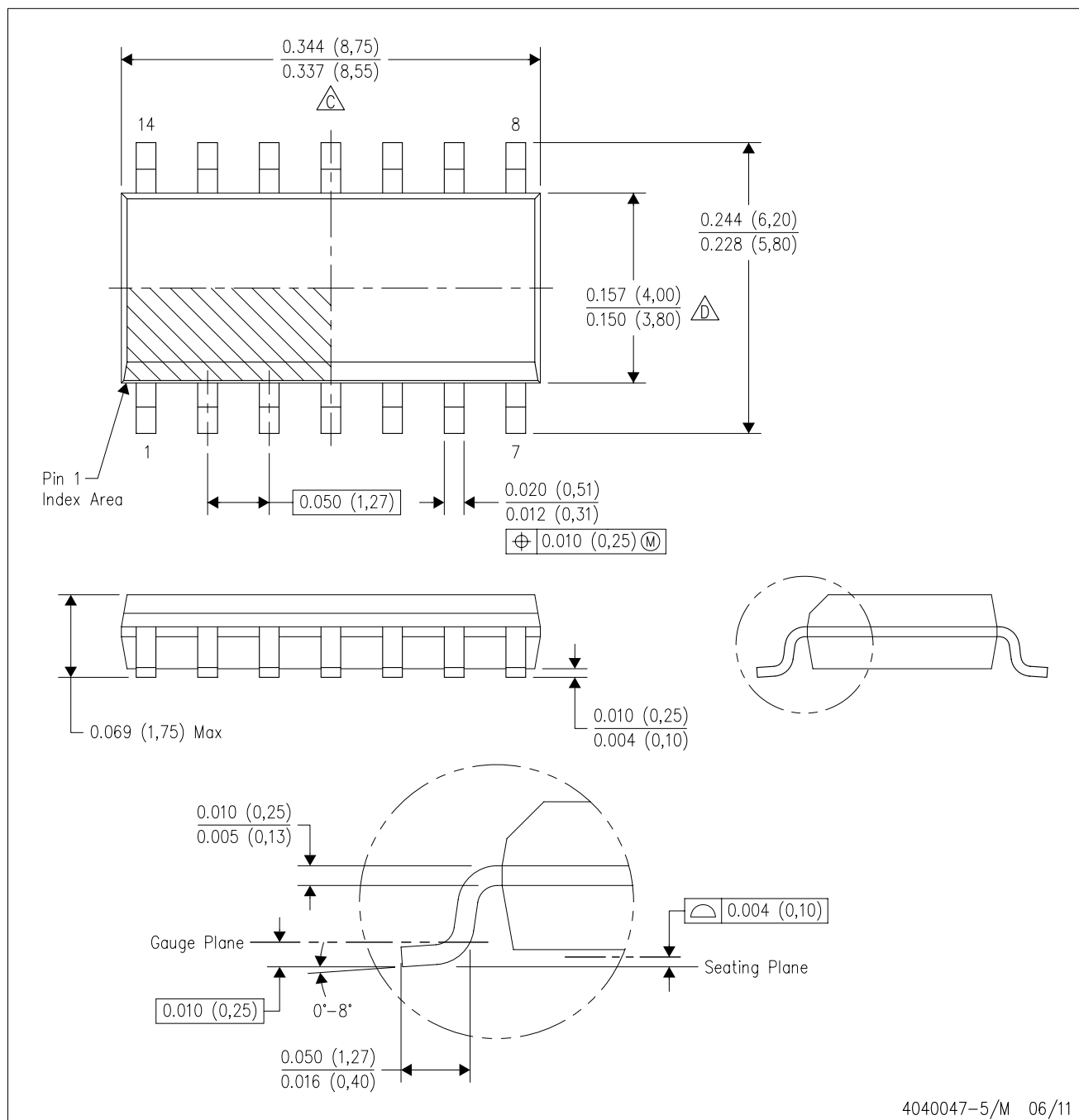
24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



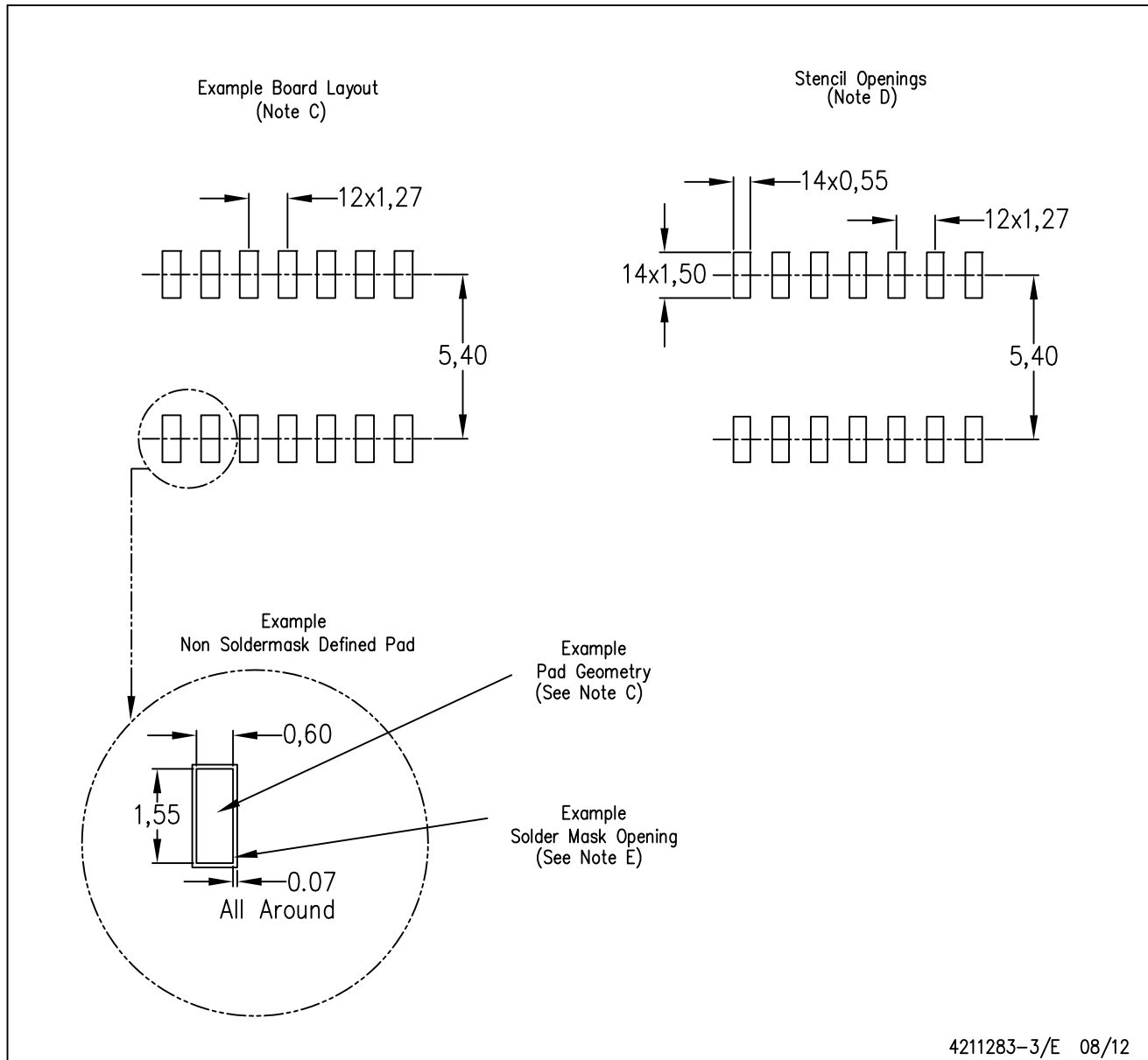
4040047-5/M 06/11

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

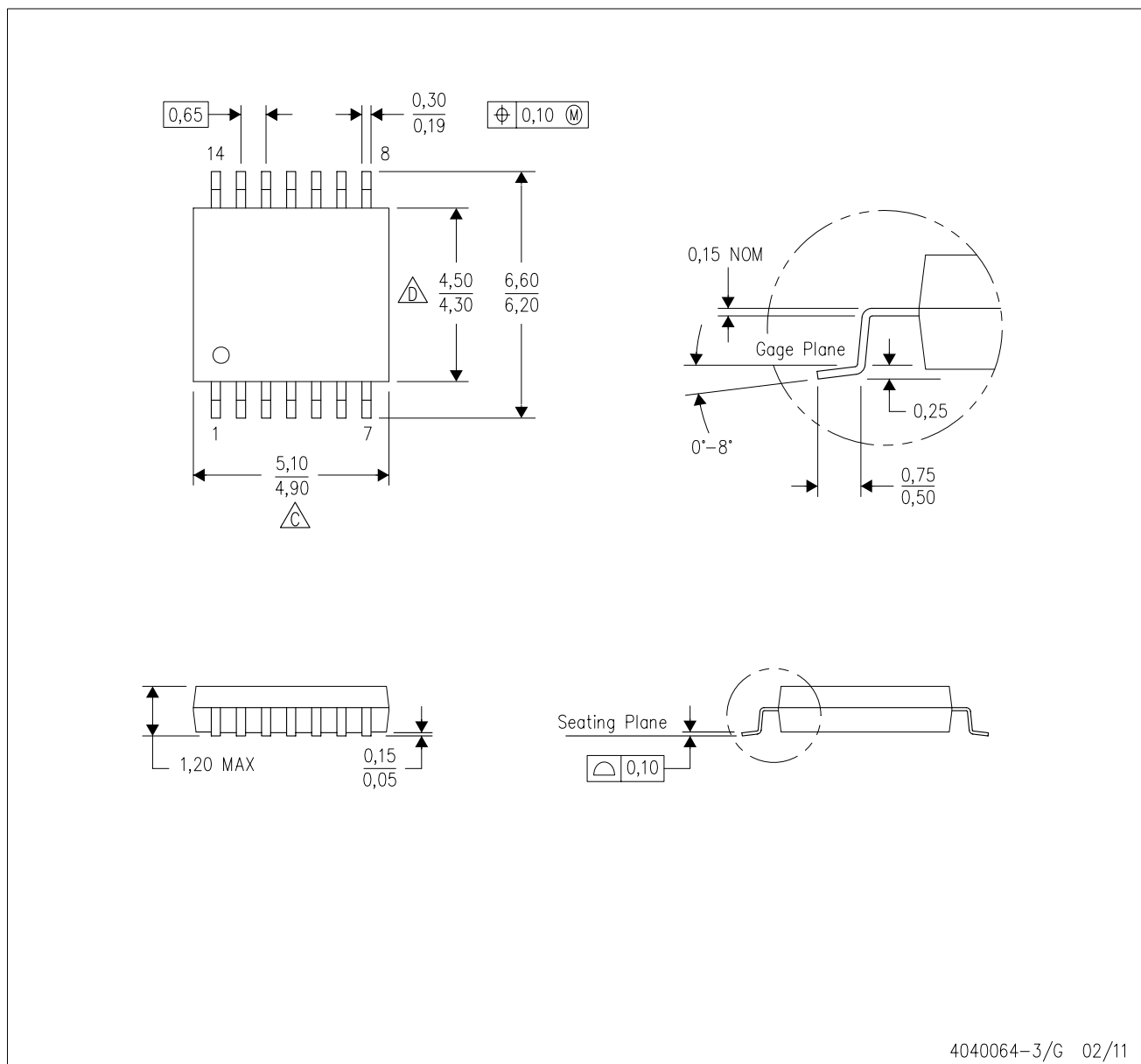
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

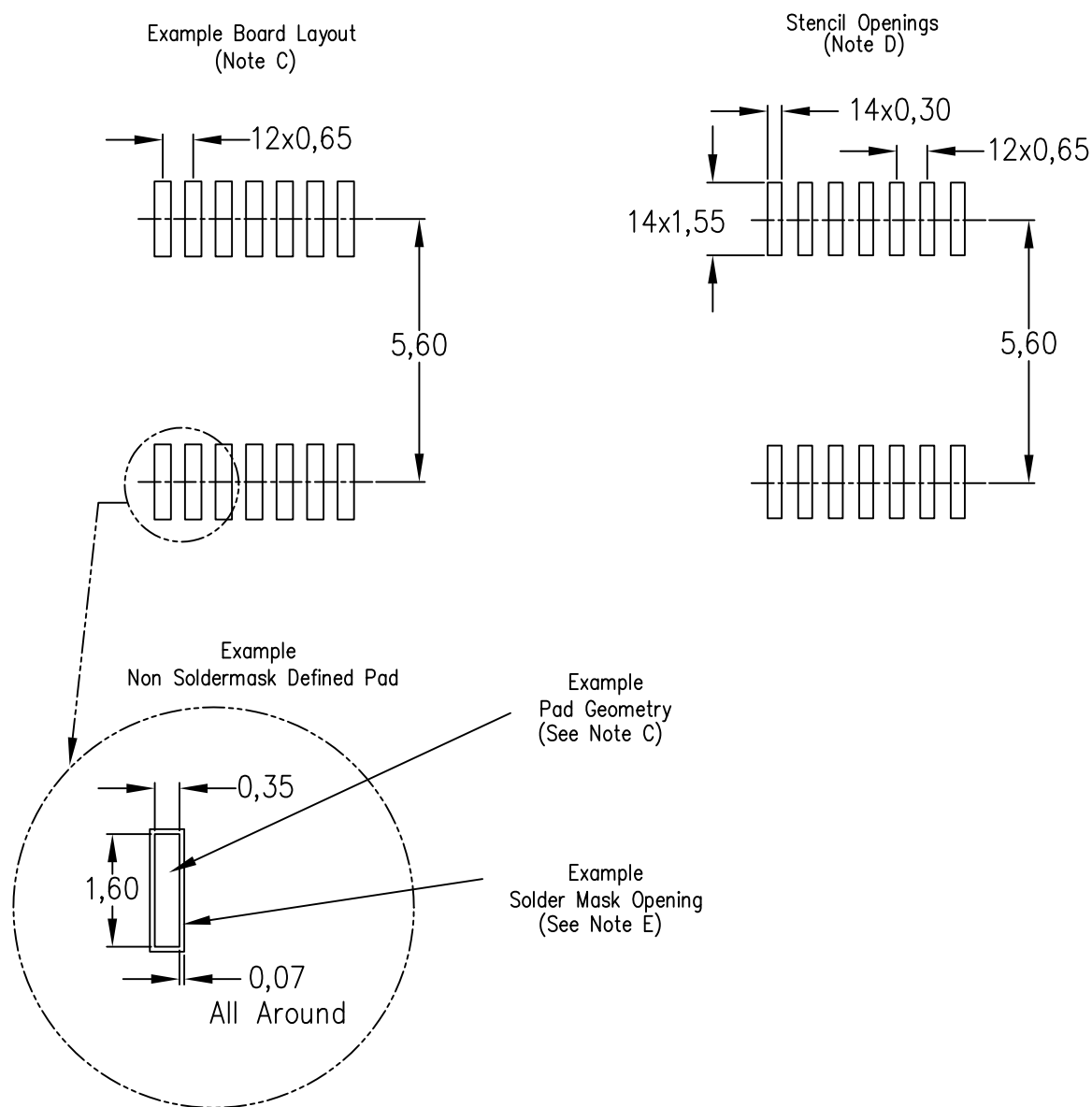
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211284-2/F 12/12

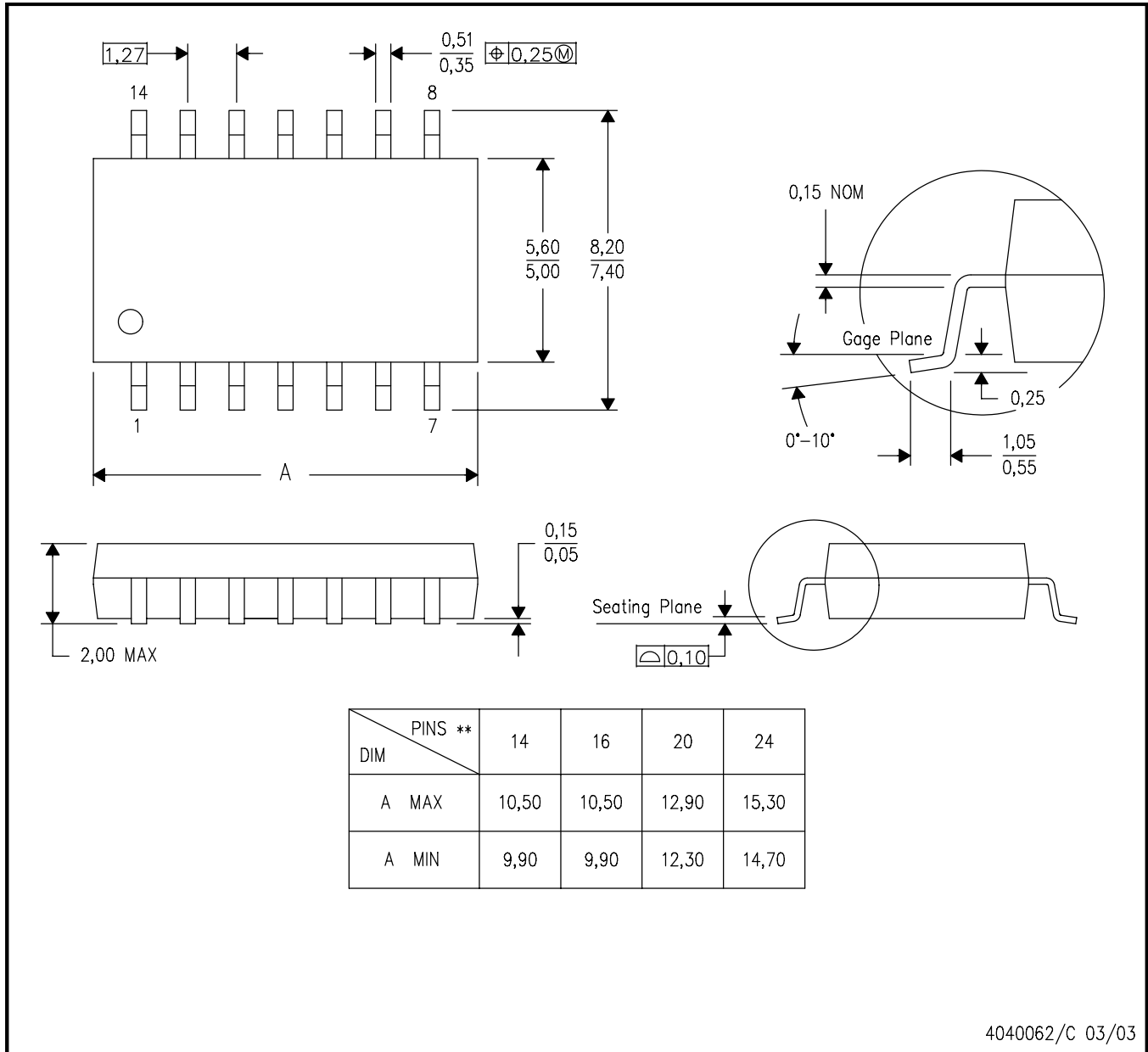
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

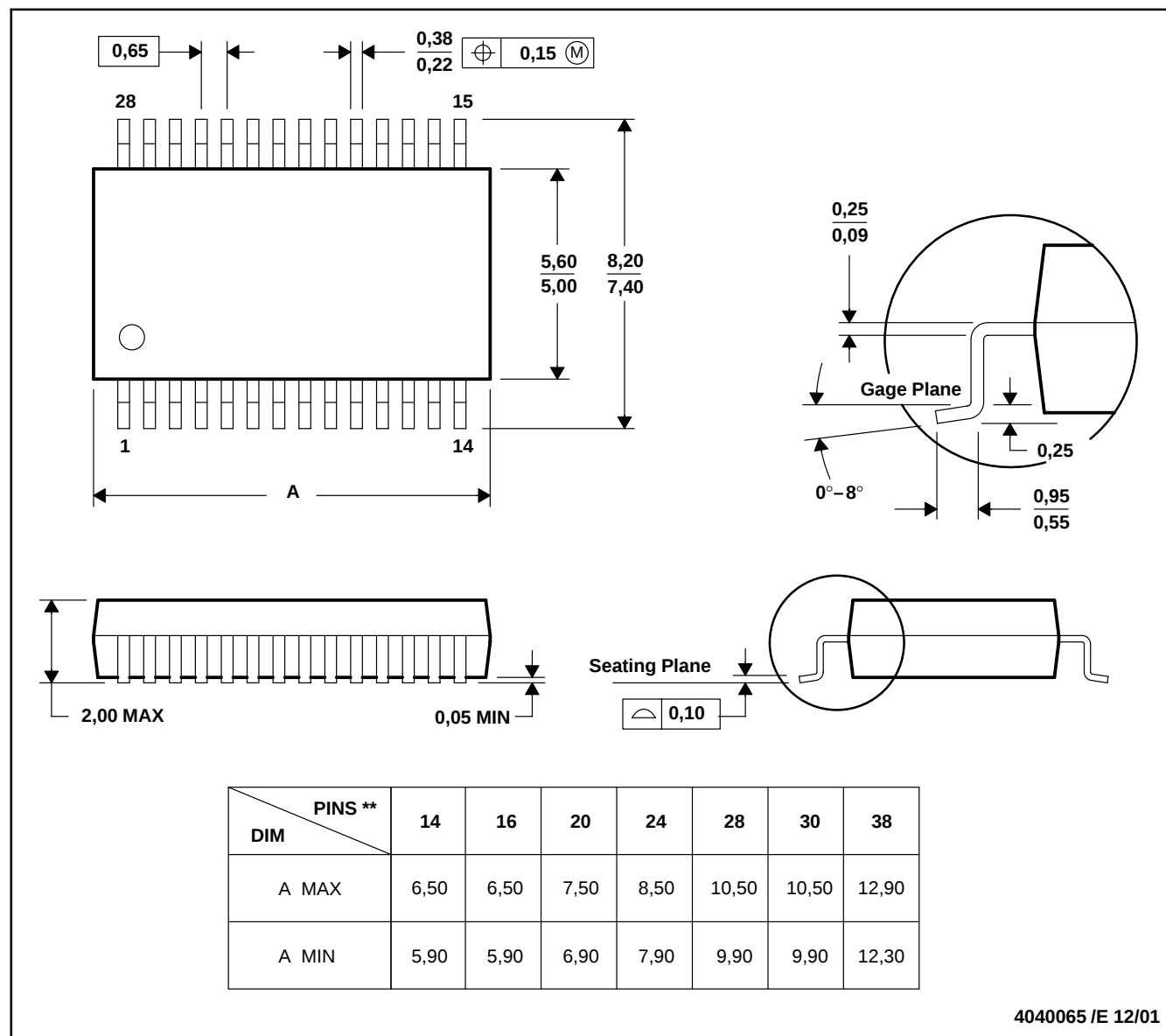


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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